

ABSTRACT

A microelectronic assembly includes a first microelectronic element having a contact bearing face and one or more contacts provided at the contact bearing face and a second microelectronic element juxtaposed with the first microelectronic element, the second microelectronic element having a first surface including one or more conductive pads. The microelectronic assembly also includes one or more conductive masses electrically interconnecting the contacts of the first microelectronic element and the conductive pads of the second microelectronic element, whereby each the conductive mass includes a first region comprising a first fusible material transformable from a solid to a liquid at a first melting temperature and a second region comprising a second fusible material transformable from a solid to a liquid at a second melting temperature that is less than the first melting temperature.

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